

Title (en)
CONTACT ASSEMBLY FOR AN ELECTRICAL CONNECTOR

Title (de)
KONTAKTANORDNUNG FÜR EINEN ELEKTRISCHEN VERBINDER

Title (fr)
ENSEMBLE CONTACT POUR CONNECTEUR ÉLECTRIQUE

Publication
EP 2815463 A1 20141224 (EN)

Application
EP 13703497 A 20130130

Priority
• US 201213399528 A 20120217
• US 2013023760 W 20130130

Abstract (en)
[origin: WO2013122740A1] A contact assembly (102) includes a conductive substrate (202), a composite layer (204), and a conductive layer (206). The conductive substrate (202) is configured to form a conductive path of the electrical connector (100). The composite layer (204) is engaged to the conductive substrate (202) and includes a dielectric material (514) with a conductive filler material (508) dispersed within the dielectric material at a concentration that is lower than a percolation threshold concentration (708) of the composite layer. The conductive layer (206) is engaged to the composite layer (204). The conductive substrate (202), the composite layer (204), and the conductive layer (206) form a capacitive element through which a signal propagation path (402) between the conductive substrate (202) and a mating contact (400) that mates with the conductive layer (206) passes.

IPC 8 full level
H01R 13/03 (2006.01); **H01R 4/58** (2006.01); **H01R 13/658** (2011.01)

CPC (source: EP)
H01B 1/22 (2013.01); **H01B 1/24** (2013.01); **H01R 13/035** (2013.01); **H01R 13/7197** (2013.01); **H01R 4/58** (2013.01); **H01R 13/6464** (2013.01); **H01R 13/6599** (2013.01); **H01R 43/16** (2013.01)

Citation (search report)
See references of WO 2013122740A1

Citation (examination)
US 2011006393 A1 20110113 - CUI JI [US]

Designated contracting state (EPC)
AL AT BE BG CH CY CZ DE DK EE ES FI FR GB GR HR HU IE IS IT LI LT LU LV MC MK MT NL NO PL PT RO RS SE SI SK SM TR

Designated extension state (EPC)
BA ME

DOCDB simple family (publication)
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